

SEMI G57-0302

GUIDE FOR STANDARDIZATION OF LEADFRAME TERMINOLOGY

This guide was technically approved by the Global Assembly and Packaging Committee and is the direct responsibility of the Japanese Assembly and Packaging Committee. Current edition approved by the Japanese Regional Standards Committee on November 26, 2001. Initially available on www.semi.org December 2001; to be published March 2002. Originally published in 1993.

1 Preface

1.1 Purpose — This guideline defines standard terminologies for all the features of leadframes used in the production of semiconductor circuits.

1.2 Significance — Use of this guide in communications between customers and vendors can reduce the errors caused by the current use of different nomenclatures for the same feature of a leadframe.

Table 1 Nomenclature for Figures

1	Die Pad
2	Die Pad Support
3	Lead Lock
4	Anchor Hole
5	Inner Lead
6	Outer Lead
7	Standard Pilot Hole
8	Pilot Hole
9	Top Rail Standard Pilot Hole Side
10	Bottom Rail
11	Lead Cut-off Notch
12	Dam Bar
13	Lead Shoulder
14	Mold Dam
15	Bumper Support Cut-off Notch
16	Lead Lock Groove
17	Mold Line
18	Expansion Slot
19	Down Set
20	Die Pad Dimple
21	Side Rail
22	Strip Cut-off Line
23	Coined Area
24	Degate Hole

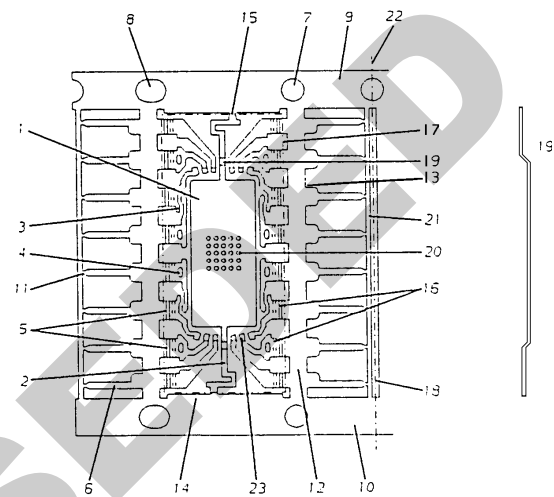


Figure 1

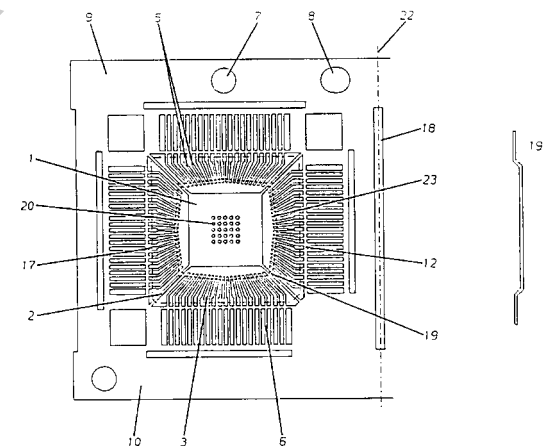


Figure 2

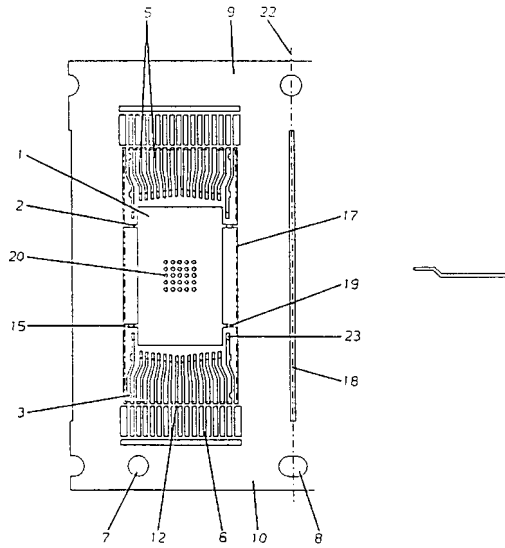


Figure 3

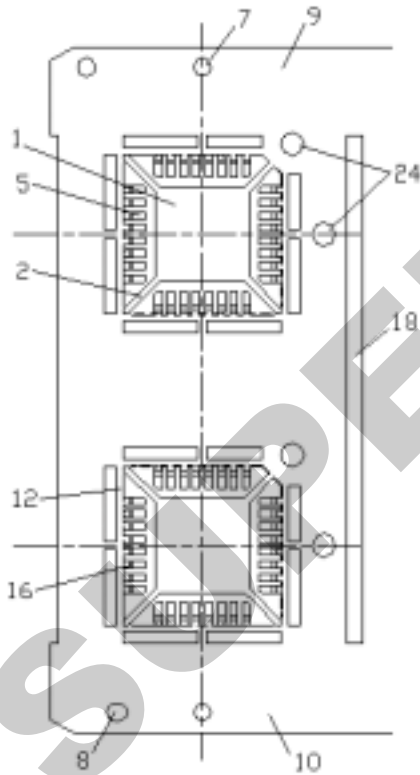


Figure 4

NOTICE: These standards do not purport to address safety issues, if any, associated with their use. It is the responsibility of the user of these standards to establish appropriate safety and health practices and determine the applicability of regulatory limitations prior to use. SEMI makes no warranties or representations as to the suitability of the standards set forth herein for any particular application. The determination of the suitability of the standard is solely the responsibility of the user. Users are cautioned to refer to manufacturer's instructions, product labels, product data sheets, and other relevant literature respecting any materials mentioned herein. These standards are subject to change without notice.

The user's attention is called to the possibility that compliance with this standard may require use of copyrighted material or of an invention covered by patent rights. By publication of this standard, SEMI takes no position respecting the validity of any patent rights or copyrights asserted in connection with any item mentioned in this standard. Users of this standard are expressly advised that determination of any such patent rights or copyrights, and the risk of infringement of such rights, are entirely their responsibility.